

## Description

The 6706A uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used to form a level shifted high side switch, and a wide variety of applications.

## General Features

### ● N-Channel

$V_{DSS}$	$R_{DS(ON)}$ @ 10V (typ)	$I_D$
30V	20 mΩ	6.5A

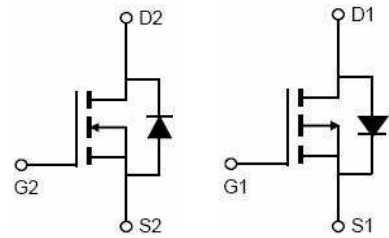
### ● P-Channel

$V_{DSS}$	$R_{DS(ON)}$ @ 10V (typ)	$I_D$
-30V	42 mΩ	-5 A

- High power and current handing capability
- RoHS Compliant

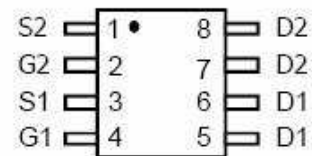
## Application

- PWM applications
- Load switch
- Power management

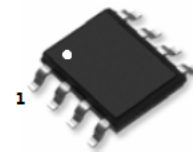


N-channel P-channel

## Schematic diagram



Marking and pin assignment



SOP-8

## Ordering Information

Part Number	Marking	Case	Packaging
6706A	6706A	SOP-8	4000pcs/Reel

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	$V_{DS}$	30	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	V
Drain Current-Continuous	$I_D$	$T_A=25^\circ\text{C}$	-5	A
		$T_A=70^\circ\text{C}$	-4.1	A
Drain Current-Pulsed (Note 1)	$I_{DM}$	26	-20	A
Maximum Power Dissipation	$P_D$	2.0	2.0	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	-55 To 150	$^\circ\text{C}$

## Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	N-Ch	62.5	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	P-Ch	62.5	$^\circ\text{C}/\text{W}$

## N-CH Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	30	33	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	1.6	2.4	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5A	-	20	30	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A	-	30	40	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =5A	-	15	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, F=1.0MHz	-	255	-	PF
Output Capacitance	C <sub>oss</sub>		-	45	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	35	-	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =15V, R <sub>L</sub> =2.5Ω V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω	-	4.5	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	2.5	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	14.5	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	3.5	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =5A, V <sub>GS</sub> =10V	-	5.2	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	0.85	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	1.3	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =5A	-	-	1.2	V

## P-CH Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-30	-33	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V	-	-	-1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1	-1.6	-2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-4A	-	42	60	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A	-	62	90	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-5V, I <sub>D</sub> =-5A	-	8	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, F=1.0MHz	-	520	-	PF
Output Capacitance	C <sub>OSS</sub>		-	100	-	PF
Reverse Transfer Capacitance	C <sub>RSS</sub>		-	65	-	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-15V, R <sub>L</sub> =2.3Ω V <sub>GS</sub> =-10V, R <sub>G</sub> =6Ω	-	7.5	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	5.5	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	19	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	7	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-15V, I <sub>D</sub> =-5A, V <sub>GS</sub> =-10V	-	9.2	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	1.6	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	2.2	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-5A	-	-	-1.2	V

### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.

N-Channel Typical Electrical and Thermal Characteristics (Curves)

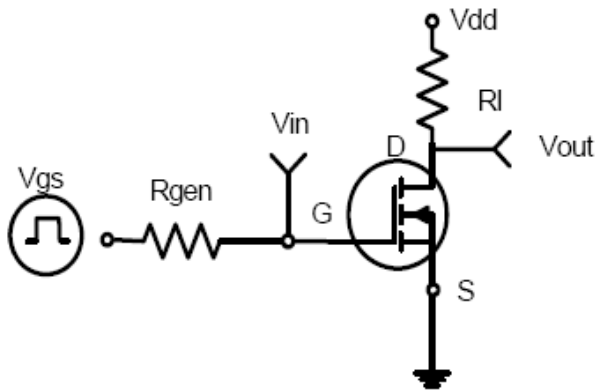


Figure 1 Switching Test Circuit

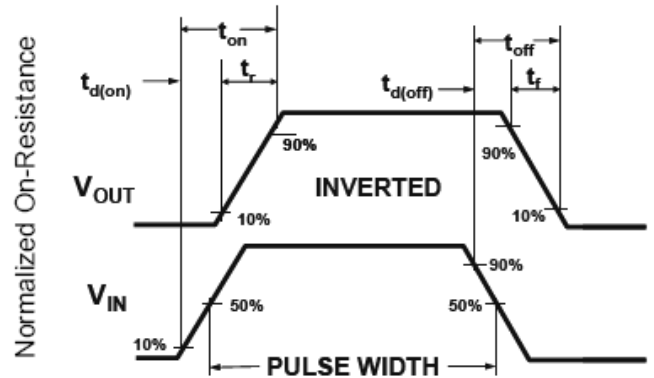


Figure 2 Switching Waveforms

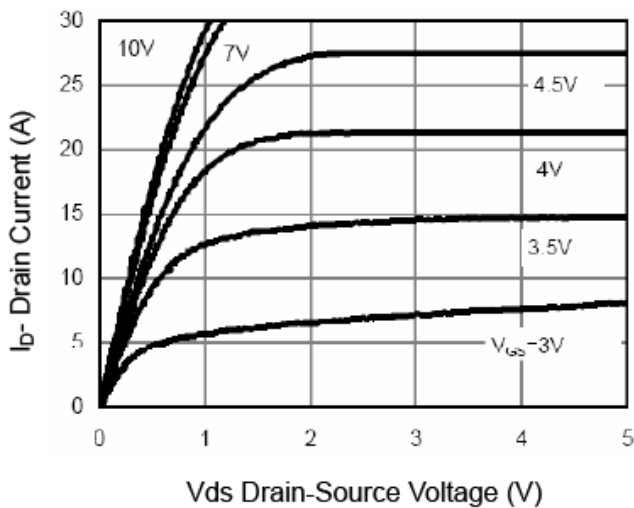


Figure 3 Output Characteristics

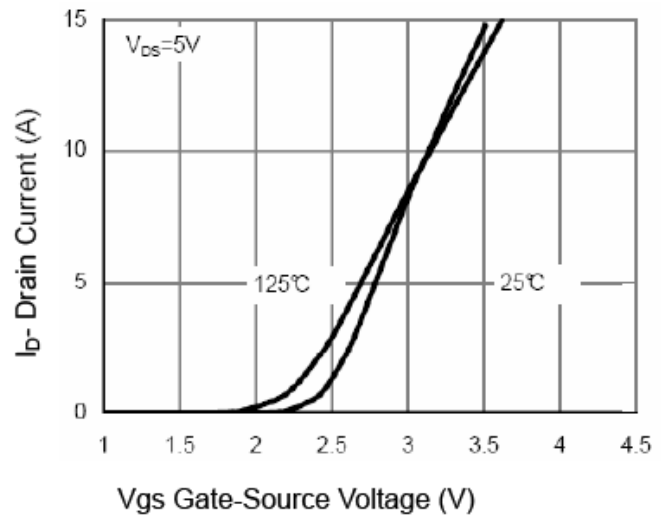


Figure 4 Transfer Characteristics

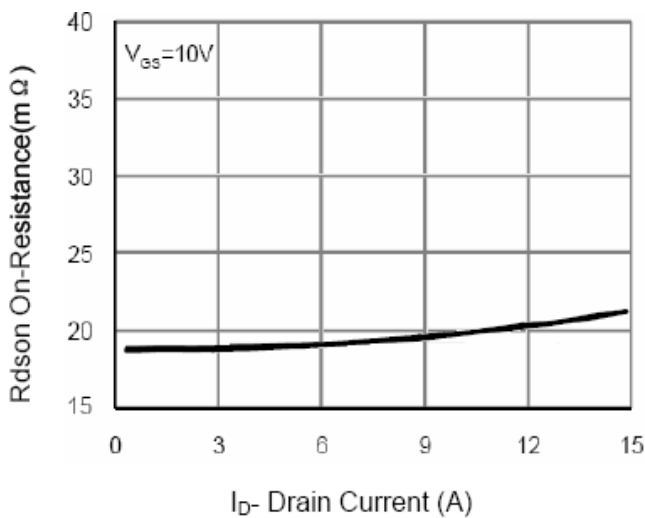


Figure 5 Rdson- Drain Current

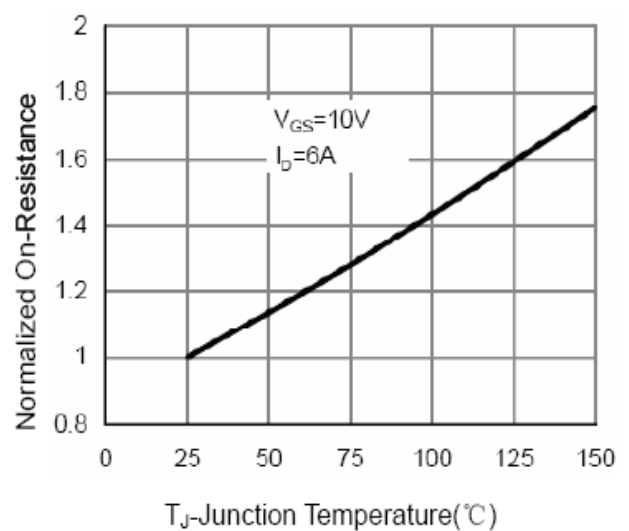


Figure 6 Source- Drain Diode Forward

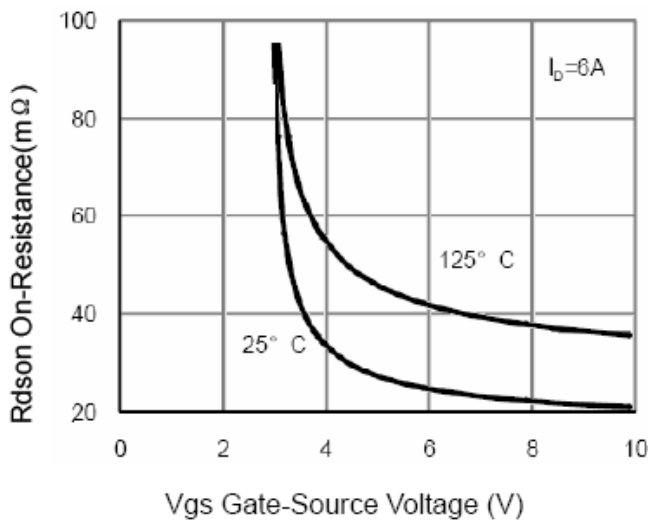


Figure 7 Rdson vs Vgs

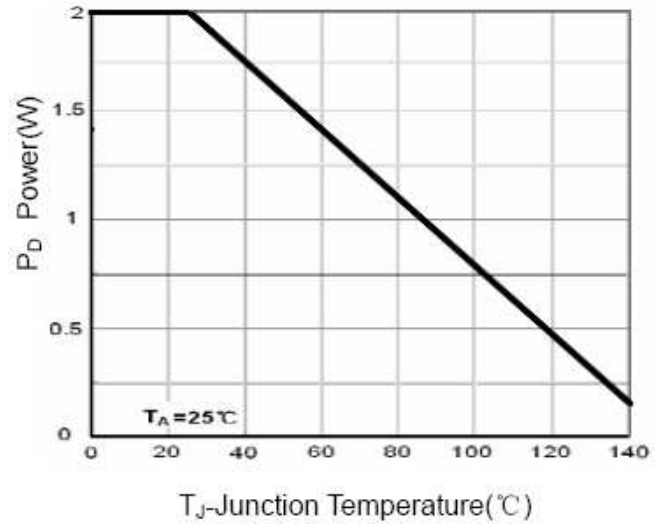


Figure 8 Power Dissipation

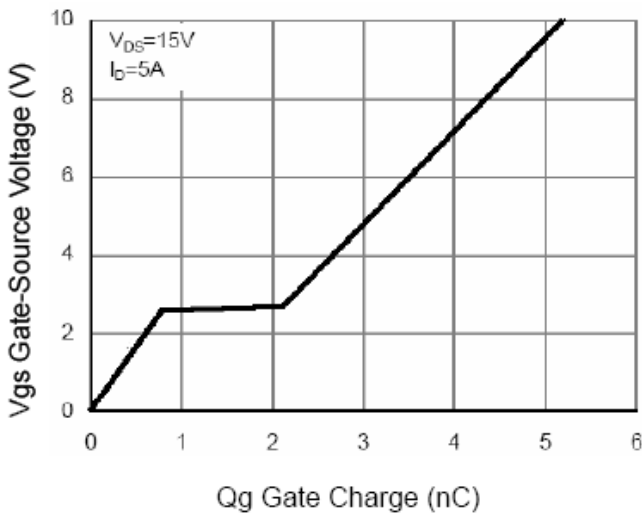


Figure 8 Gate Charge

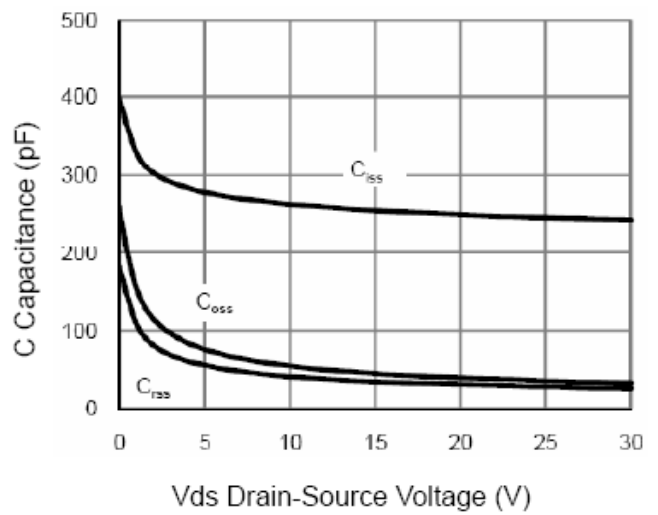


Figure 9 Capacitance vs Vds

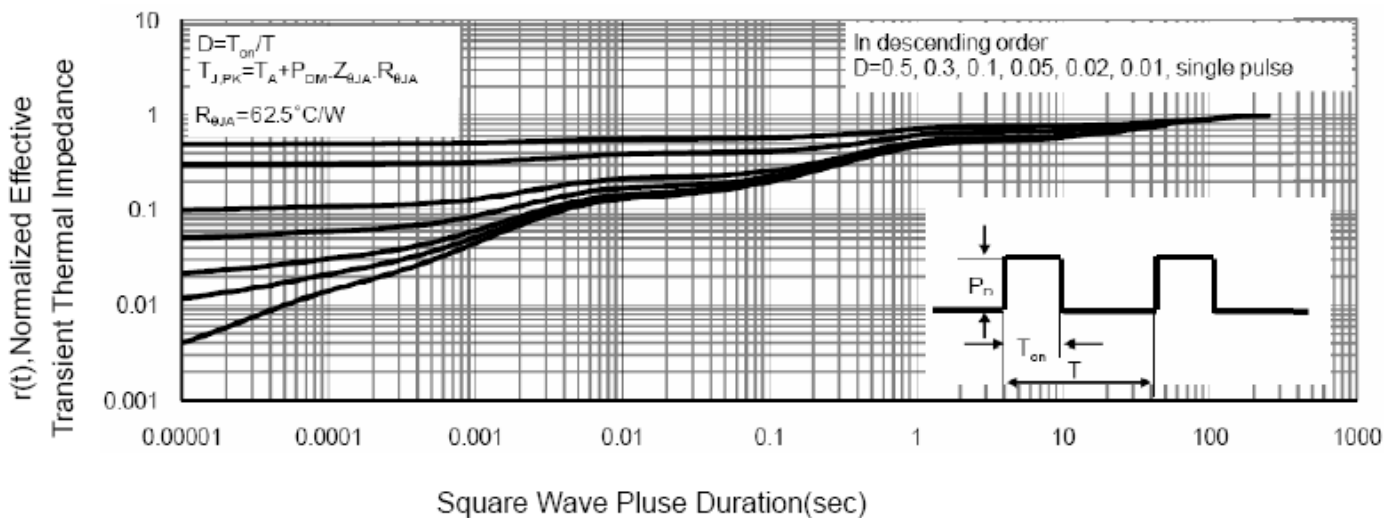


Figure 10 Normalized Maximum Transient Thermal Impedance

P-Channel Typical Electrical and Thermal Characteristics (Curves)

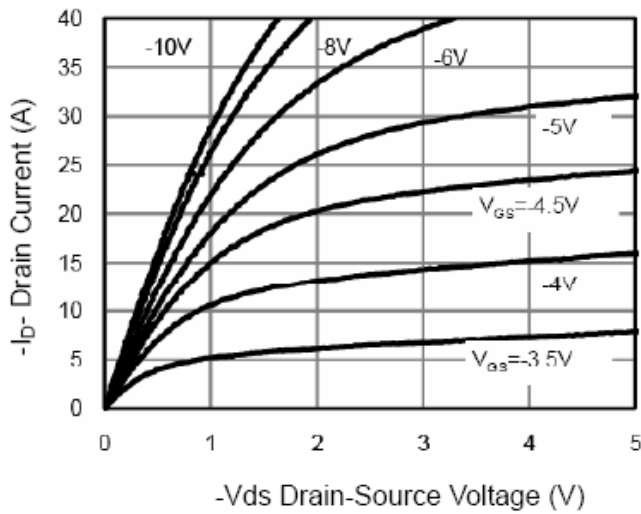


Figure 1 Output Characteristics

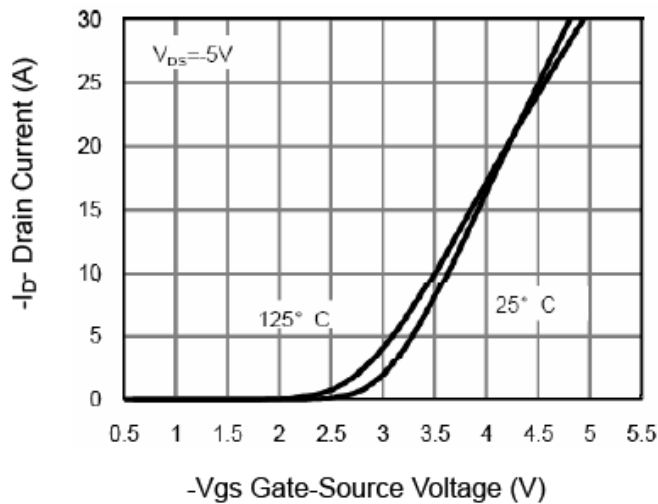


Figure 3 Transfer Characteristics

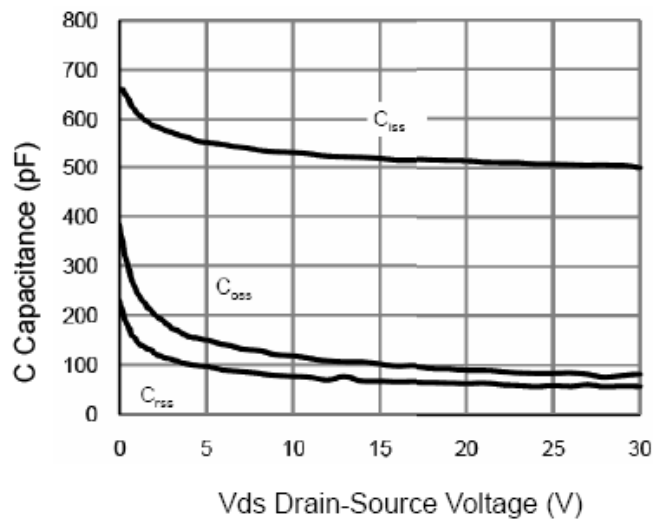


Figure 5 Capacitance vs Vds

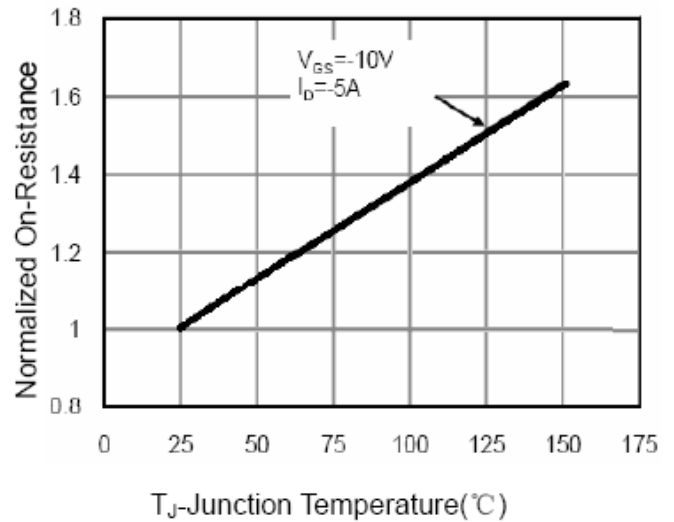


Figure 2  $R_{dson}$ -Junction Temperature

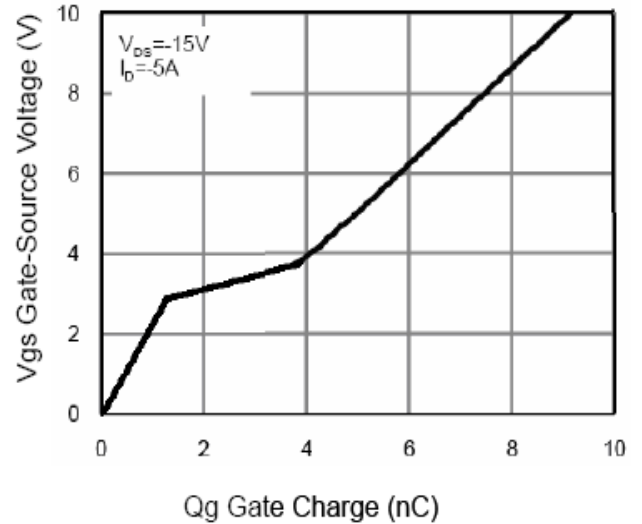


Figure 4 Gate Charge

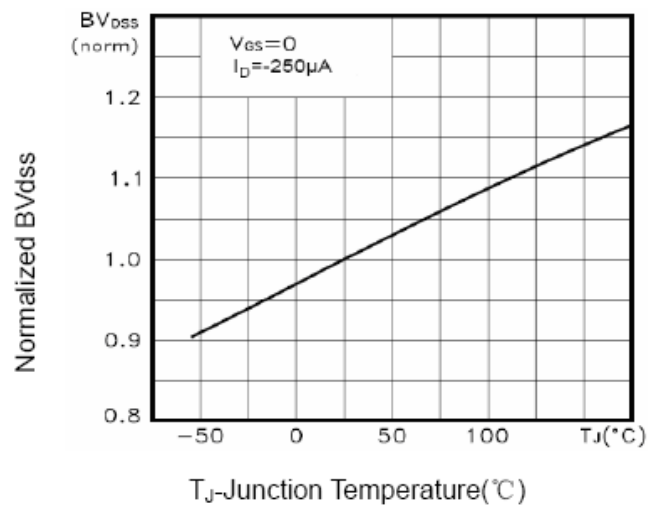


Figure 6  $BV_{DSS}$  vs Junction Temperature

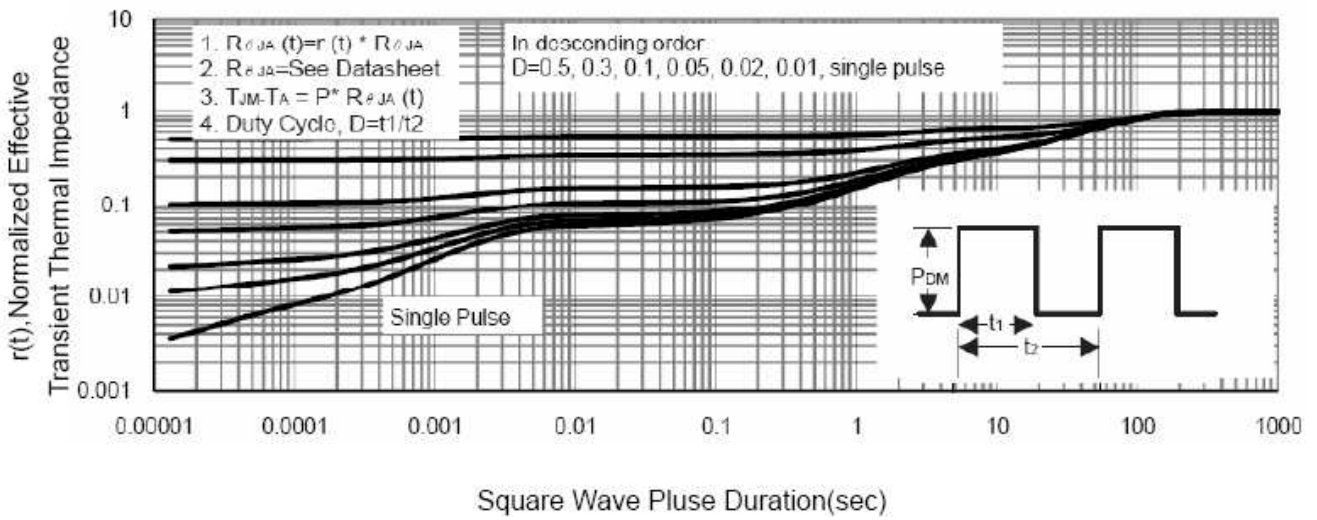
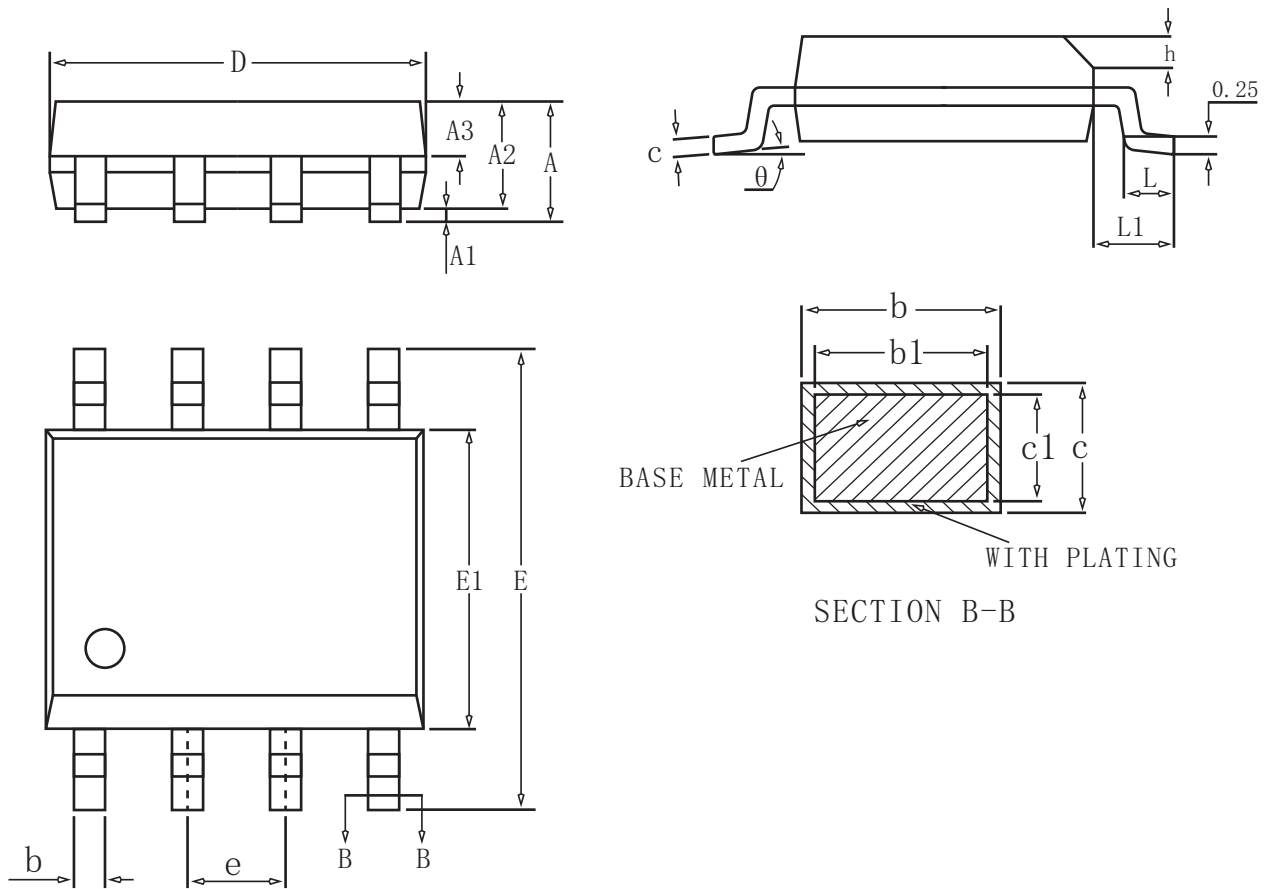


Figure 7 Normalized Maximum Transient Thermal Impedance

## Package information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	-	-	1.75
A1	0.10	-	0.225
A2	1.30	1.40	1.50
A3	0.60	0.65	0.70
b	0.39	-	0.47
b1	0.38	0.41	0.44
c	0.20	-	0.24
c1	0.19	0.20	0.21
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e	1.27BSC		
h	0.25	-	0.50
L	0.50	-	0.80
L1	1.05REF		
$\theta$	0	-	8°